

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	"6551906".pn.	USPAT	OR	OFF	2008/09/05 14:52
L2	1	"5516858".pn.	USPAT	OR	OFF	2008/09/05 14:52
L3	1	"5726219".pn.	USPAT	OR	OFF	2008/09/05 14:53
L4	1	"5118567".pn.	USPAT	OR	OFF	2008/09/05 14:53
S1	2205	438/780	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 10:38
S2	574	S1 AND 438/781	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 10:39
S3	231	S2 AND (protect OR protecting OR protect \$3 OR protected)	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 10:40
S4	2	S3 AND (grind OR grinding OR grind\$3)	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 10:43
S5	4307027	semiconductor OR circuit OR IC	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 11:04
S6	4380268	semiconductor OR circuit OR IC OR wafer	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 11:05
S7	424	S6 AND (surface NEAR protect\$3 NEAR2 method)	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 11:06
S8	1	"10595678"	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 11:19

S9	38687	S5 AND ((meth NEAR1 acrylates) OR pentaerythritol OR urethane OR phenol-novolac OR cresol-novolac)	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 11:23
S10	68	S9 AND (surface NEAR protect\$3 NEAR2 method)	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 11:24
S11	0	"6792991".pn. "6235141".pn.	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 11:27
S12	2	"6792991".pn.	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 11:28
S13	2	"6235141".pn.	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 11:28
S14	2	"5476566".pn.	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 11:28
S15	2	"6284425".pn.	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 11:37
S16	2	"6358664".pn.	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 11:38
S17	2	"20010018404"	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 11:38
S18	0	"4818323".pn. "5414297".pn.	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 11:39
S19	0	"4818323"" .pn.", "5414297".pn.	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 11:39
S20	2	"4818323".pn.	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 11:39

S21	2	"5414297".pn.	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 11:40
S22	2	"6214520".pn.	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 11:40
S23	2	"6551906".pn.	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 11:40
S24	2	"6620649".pn.	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 12:17
S25	2	"6939741".pn.	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 12:19
S26	4	"7201969".pn.	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 12:19
S27	570	S6 AND ((storage NEAR1 elastic NEAR1 modulus) OR (elastic NEAR1 shear NEAR1 storage NEAR1 modulus))	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 12:25
S28	8	S27 AND S10	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 12:25
S29	1057813	S6 AND ((storage NEAR1 elastic NEAR1 modulus) OR E' OR (elastic NEAR1 tensile NEAR1 storage NEAR1 modulus))	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 12:29
S30	570	S29 AND S27	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 12:30
S31	8	S30 AND S28	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 12:30

S32	4380268	semiconductor OR circuit OR IC OR wafer	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 14:22
S33	783	S32 AND (UV NEAR1 curing NEAR1 resin)	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 14:22
S34	369	S33 AND (resin SAME (heated OR heat OR heat\$3))	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 14:23
S35	20	S34 AND (solid SAME (room NEAR temperature))	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 14:24
S36	1	S35 AND (fluid WITH (heat OR heating OR heated OR heat\$3))	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 14:39
S37	5	"6674158"	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 15:58
S38	0	"6674158.pn."	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 15:58
S39	2	"6674158".pn.	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 15:58
S41	4307027	semiconductor OR circuit OR IC	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 18:33
S42	38687	S41 AND ((meth NEAR1 acrylates) OR pentaerythritol OR urethane OR phenol-novolac OR cresol-novolac)	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 18:33
S43	1	S41 AND (phenol NEAR1 novolac NEAR1 meth NEAR1 acrylate)	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 18:41
S44	1	S41 AND (phenol NEAR1 novolac NEAR1 acrylate)	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 18:41

S45	18	"5516858"	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 18:47
S46	2	"5516858".pn.	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 18:47
S47	2	"5726219".pn.	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 18:53
S48	2	"4963602".pn.	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 19:22
S49	1818	S41 AND (phenol NEAR1 novolac)	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 19:33
S50	1031	S49 AND ((molecular NEAR1 weight) OR MW)	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 19:34
S51	161	S49 AND (((molecular NEAR1 weight) OR MW) NEAR2 "1000")	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 19:34
S52	21	S49 AND ((phenol NEAR1 novolac) SAME (((molecular NEAR1 weight) OR MW) NEAR2 "1000"))	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 19:42
S53	0	S52 AND initiator	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 19:42
S54	11	S52 AND initiator	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 19:42
S55	1	S52 AND (cationic NEAR1 initiator)	US-PGPUB; USPAT; DERWENT; IBM_TDB	AND	OFF	2008/09/04 19:42

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